

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16278
1.3 Title of PCN	STM32C53x and STM32C54x - Product Enhancement
1.4 Product Category	STM32C531x, STM32C532x and STM32C542x
1.5 Issue date	2026-07-15

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	ST Crolles 300 (France)

4. Description of change

	Old	New
4.1 Description	Current STM32C531x, STM32C532x and STM32C542x (Revision Z) products have limitations as described in Errata Sheet ES0676 - Rev 1- February 2026	STM32C531x, STM32C532x and STM32C542x (New Revision Y) products enhancements. fixes main issues as listed below System - Access permission faults are prioritized over unaligned device memory faults - Low-speed external clock in analog bypass mode might not work properly - LSE crystal oscillator may be disturbed by transitions on PC13 - LSE low drive mode is not functional ADC - In simultaneous regular mode, stopping an injected conversion may shift the next regular conversion master and slave timing by one clock cycle - Injected conversions do not work when SMPTRIG bit is set, regular conversions start then stop, and SMPTRIG bit is cleared COMP - Simultaneous operation of COMP1 and COMP2 is not supported RNG - RNG may report continuous seed errors in specific environmental conditions as described in Errata Sheet ES0676 - Rev 2 - June 2026
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change

5.1 Motivation	Improvements implemented to fix bugs.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change			
6.1 Description		Traceability ensured by ST internal tools. Die revision changes from "Z" to "Y" on Package Marking	

7. Timing / schedule			
7.1 Date of qualification results		2026-08-07	
7.2 Intended start of delivery		2026-09-30	
7.3 Qualification sample available?		Upon Request	

8. Qualification / Validation					
8.1 Description		16278 MDRF-GPAM RER2425 - PCN16278 STM32C5x - Die 44F_Y cut1.2 - Rel plan.pdf			
8.2 Qualification report and qualification results		Available (see attachment)	<table border="1"> <tr> <td>Issue Date</td> <td>2026-07-15</td> </tr> </table>	Issue Date	2026-07-15
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9. Attachments (additional documentations)	
16278 Public product.pdf 16278 MDRF-GPAM RER2425 - PCN16278 STM32C5x - Die 44F_Y cut1.2 - Rel plan.pdf 16278 _Additional information.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32C542CCT6	
	STM32C542CCU6	
	STM32C542KCT6	
	STM32C542KCU6	
	STM32C542RCT6	
	STM32C531CBT6	
	STM32C531KBT6	
	STM32C531RBT6	
	STM32C532CBT6	
	STM32C532KBT6	
	STM32C532RBT6	

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